

ABSTRACT

A method for making UBM (Under Bump Metallurgy) pads and bumps on a wafer is disclosed. Openings are formed in a photoresist layer for forming bumps, a positive liquid photoresist is provided into the openings of the photoresist layer for forming bumps. The positive liquid photoresist is exposed and developed to modify the openings of the photoresist layer. Thus, bumps formed in the modified openings have precise bonding areas on the UBM layer. Using the bumps as a mask, UBM pads under the bumps are formed by etching the UBM layer, so that the reflowed bumps have an uniform height.